

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>TOHRU KAWAI</td> <td>01/21/2014</td> </tr> <tr> <td>TAKASHI INOUE</td> <td>01/21/2014</td> </tr> <tr> <td>TATSUO NAKAYAMA</td> <td>02/04/2014</td> </tr> <tr> <td>YASUHIRO OKAMOTO</td> <td>02/04/2014</td> </tr> <tr> <td>HIRONOBU MIYAMOTO</td> <td>02/04/2014</td> </tr> </tbody> </table>		Name	Execution Date	TOHRU KAWAI	01/21/2014	TAKASHI INOUE	01/21/2014	TATSUO NAKAYAMA	02/04/2014	YASUHIRO OKAMOTO	02/04/2014	HIRONOBU MIYAMOTO	02/04/2014
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HIRONOBU MIYAMOTO	02/04/2014												
RECEIVING PARTY DATA													
Name:	RENESAS ELECTRONICS CORPORATION												
Street Address:	1753, SHIMONUMABE, NAKAHARA-KU												
City:	KAWASAKI-SHI, KANAGAWA												
State/Country:	JAPAN												
Postal Code:	211-8668												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14188462</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14188462								
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Application Number:	14188462												
CORRESPONDENCE DATA													
Fax Number:	(703)761-2375												
Phone:	703 761 4100												
Email:	admin@mcginniplaw.com												
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>													
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ATTORNEY DOCKET NUMBER:	TSUT.005												
NAME OF SUBMITTER:	SEAN M.MCGINN												

Signature:	/Sean M.McGinn/
Date:	03/04/2014
Total Attachments: 2 source=TSUT.005#page1.tif source=TSUT.005#page2.tif	

ASSIGNMENT

(讓渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Electronics Corporation, a corporation organized under the laws of Japan, located at 1753, Shimonumabe, Nakahara-ku, Kawasaki-shi, Kanagawa 211-8668, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Electronics Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Renesas Electronics Corporation,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Electronics Corporation.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Tohru KAWAI</u> (Tohru KAWAI)	<u>January 21, 2014</u>
2) _____ (Takashi INOUE)	_____
3) <u>Tatsuo NAKAYAMA</u> (Tatsuo NAKAYAMA)	<u>February 4, 2014</u>
4) <u>Yasuhiro OKAMOTO</u> (Yasuhiro OKAMOTO)	<u>February 4, 2014</u>
5) <u>Hironobu MIYAMOTO</u> (Hironobu MIYAMOTO)	<u>February 4, 2014</u>
6) _____	_____

ASSIGNMENT
(譲渡証)

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And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Electronics Corporation.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1)	_____ (Tohru KAWAI)	_____
2)	<u>Takashi Inoue</u> _____ (Takashi INOUE)	<u>January 21st, 2014</u>
3)	_____ (Tatsuo NAKAYAMA)	_____
4)	_____ (Yasuhiro OKAMOTO)	_____
5)	_____ (Hironobu MIYAMOTO)	_____
6)	_____	_____